

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1.-29. (Cancelled).

30. (New) A socket for receiving an electronic device having connector pins and alignment tabs, said socket comprising:

an upper surface;

a plurality of receptacles in said upper surface for receiving the connector pins;

a plurality of apertures in said upper surface for receiving the alignment tabs, wherein said apertures are arranged so as to align the connector pins and said receptacles as the apertures receive the alignment tabs;

an arm extending from the socket; and

a locking lever pivotally connected to said arm, wherein said locking lever has a first position wherein the electronic device is locked to the socket and a second position wherein the electronic device can be removed from the socket.

31. (New) The socket of claim 30 wherein said locking lever is elevated above said upper surface in both the first and second positions.

32. (New) The socket of claim 30 wherein the electronic device includes at least one tab arranged so as to prevent engagement of the electronic device and said socket when said locking lever is in the first position.

33. (New) The socket of claim 30 wherein said apertures are arranged around the perimeter of said upper surface.

34. (New) The socket of claim 30 wherein the electronic device includes a heat sink having a larger footprint than said socket and said locking lever can be actuated when the electronic device and heat sink are engaged with said socket.

35. (New) The socket of claim 30 wherein said receptacles are arranged in a grid array for receiving the connector pins arranged in a corresponding grid array.

36. (New) An assembly comprising:
a circuit board;
a socket connected to said circuit board and comprising an upper surface having a plurality of receptacles;
an electronic device having a plurality of connector pins disposed in the receptacles of said socket;
an alignment cage connected to said electronic device and having a plurality of alignment tabs arranged to interface with said socket to align the connector pins with the receptacles;
a heat sink attached to said alignment cage and in thermal contact with said electronic device, wherein said heat sink has a footprint extending beyond both said electronic device and said socket;
a plurality of alignment pins protruding from said heat sink and arranged to interface with a corresponding number of holes in said circuit board so as to align the alignment tabs with said socket;
a locking lever pivotally connected to an arm extending from said socket to a position outside of the footprint of said heat sink.

37. (New) The assembly of claim 36 wherein said locking lever has a first position wherein the electronic device is locked to the socket and a second position wherein the electronic device can be removed from the socket; wherein both said locking lever is at an angle to said circuit board in both the first and second positions.

38. (New) The assembly of claim 37 further comprising a tab that prevents engagement of said electronic device and said socket when said locking lever is in the first position.

39. (New) The assembly of claim 36 wherein said socket further comprises a plurality of apertures arranged to interface with the alignment tabs of said alignment cage.

40. (New) The assembly of claim 36 wherein said alignment pins extend past the alignment tabs of said alignment cage and the alignment tabs extend past the connector pins of said electronic device.

41. (New) A method for installing a chip and heat sink assembly to a socket mounted on a circuit board, the method comprising:

attaching the chip to an alignment cage disposed on the heat sink assembly;

inserting alignment pins protruding from the heat sink assembly into holes in the circuit board;

moving the heat sink assembly toward the circuit board to first engage the alignment cage and the socket and then engage the chip and the socket; and

actuating a locking lever to lock the chip to the socket, wherein the locking lever is mounted to an arm extending from the socket.

42. (New) The method of claim 41 wherein observation of the engagement of the alignment cage and the chip with the socket is obscured by the heat sink.

43. (New) The method of claim 41 wherein the alignment cage has a plurality of tabs arranged so as to interface with a plurality of apertures in the socket in order to align the chip and the socket before pins protruding from the chip engage receptacles on the socket.

44. (New) A computer system comprising:
a circuit board;
a socket mounted to said circuit board;
an electronic device having pins engaged with receptacles on said socket;
a cage attached to said electronic device and engaged with said socket;
a heat sink connected to said cage and in thermal contact with said electronic device, wherein said heat sink has a perimeter that extends beyond said socket;
means for aligning said heat sink with said circuit board;
means for aligning said cage and said socket;
means for aligning the pins of said electronic device with and the receptacles of said socket; and
a locking lever rotatably mounted to an arm extending from said socket.
45. (New) The system of claim 44 wherein said means for aligning said heat sink with said circuit board provides gross alignment between said cage and said socket.
46. (New) The system of claim 45 wherein said means for aligning said cage and said socket provides alignment between said electronic device and said socket.
47. (New) The system of claim 44 wherein said means for aligning the pins of said electronic device with and the receptacles of said socket is not engaged until said means for aligning said cage and said socket is engaged.
48. (New) The system of claim 47 wherein means for aligning said cage and said socket is not engaged until said means for aligning said heat sink with said circuit board is engaged.

49. (New) The system of claim 44 wherein said locking lever has a locked position securing said electronic device to said socket and an unlocked position allowing said electronic device to be moved relative to said socket.

50. (New) The system of claim 49 wherein said locking lever is elevated above said circuit board in both the locked and unlocked position.

51. (New) The system of claim 44 wherein said locking lever extends from said socket to a position not under said heat sink.

52. (New) The system of claim 44 wherein the pins of said electronic device are arranged in a grid array.

53. (New) The system of claim 52 wherein the receptacles on said socket are arranged in a corresponding grid array operable to receive the pins of said electronic device.